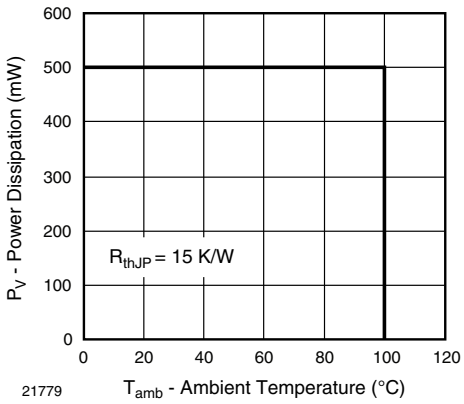


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

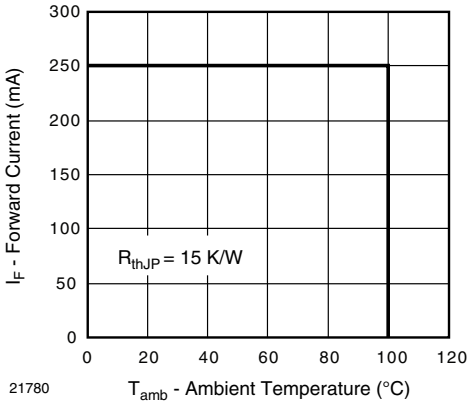


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Forward voltage	I_F = 250 mA, t_p = 10 ms	V_F	-	1.7	2.0	V
Temperature coefficient of V_F	I_F = 1 mA	TK_{VF}	-	-1.5	-	mV/K
Reverse current	V_R = 5 V	I_R	Not designed for reverse operation			µA
Radiant intensity	I_F = 250 mA, t_p = 10 ms	I_e	30	55	90	mW/sr
Radiant power	I_F = 250 mA, t_p = 20 ms	ϕ_e	-	130	-	mW
Temperature coefficient of ϕ_e	I_F = 1 A	$TK\phi_e$	-	-0.5	-	%/K
Angle of half intensity		φ	-	± 60	-	°
Peak wavelength	I_F = 250 mA	λ_p	-	850	-	nm
Spectral bandwidth	I_F = 250 mA	$\Delta\lambda$	-	30	-	nm
Temperature coefficient of λ_p	I_F = 250 mA	$TK\lambda_p$	-	0.2	-	nm/K
Rise time	I_F = 250 mA	t_r	-	8	-	ns
Fall time	I_F = 250 mA	t_f	-	10	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

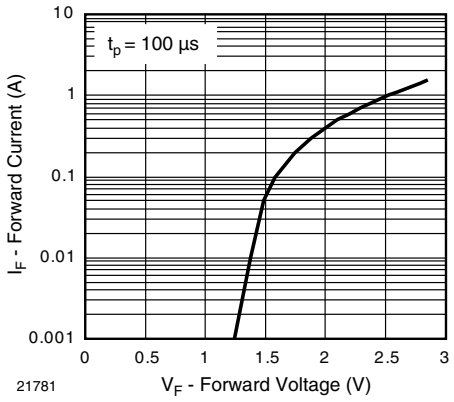


Fig. 3 - Forward Current vs. Forward Voltage

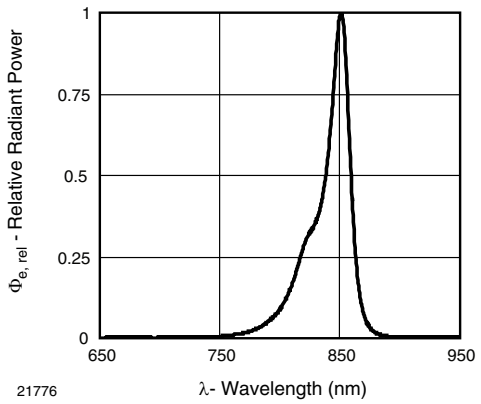


Fig. 5 - Relative Radiant Power vs. Wavelength

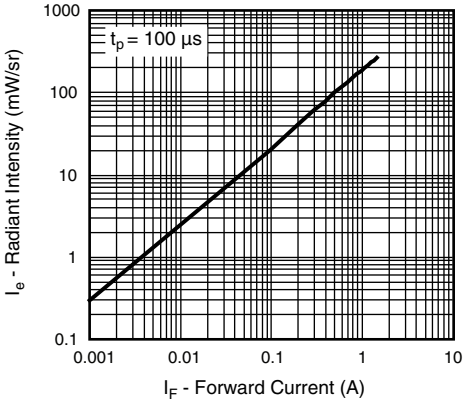


Fig. 4 - Radiant Intensity vs. Forward Current

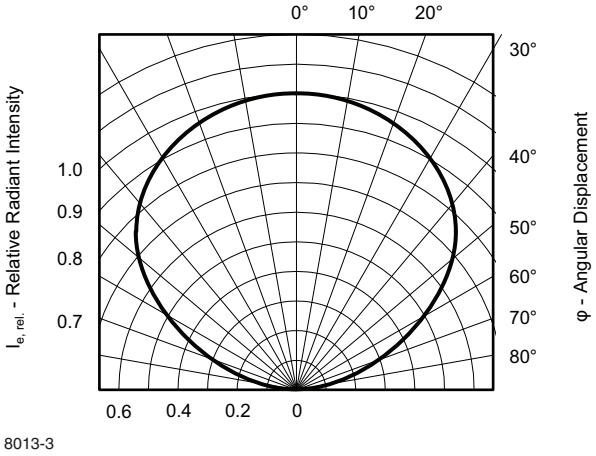
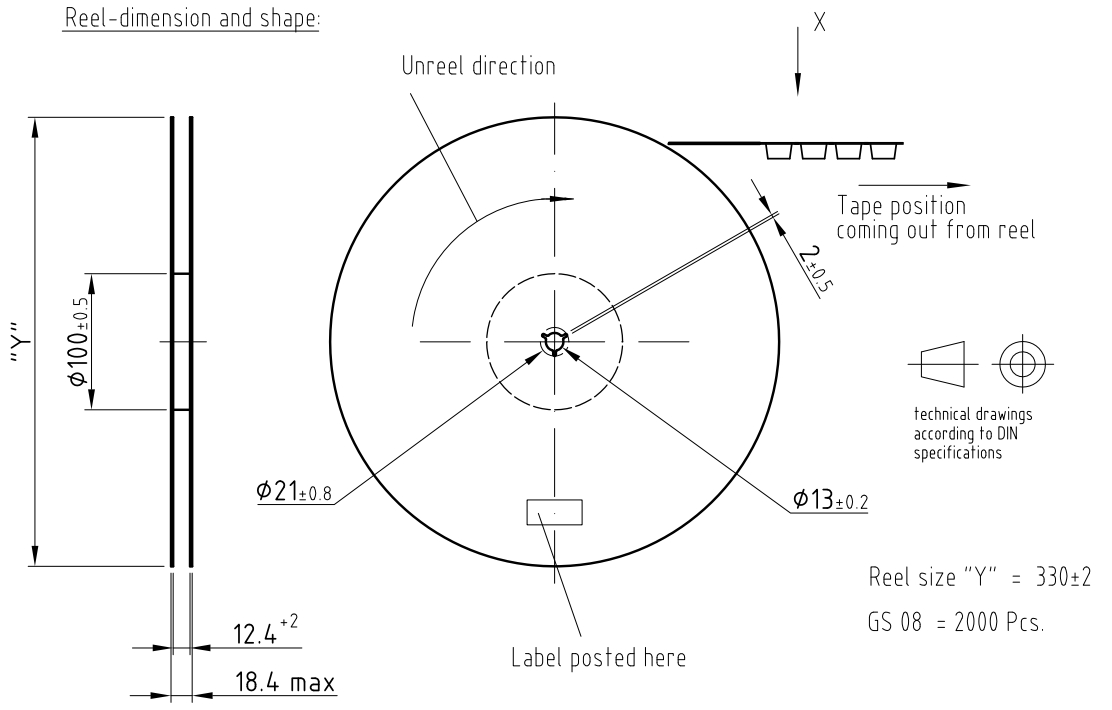
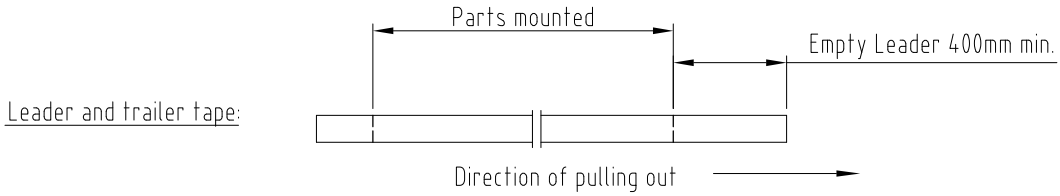
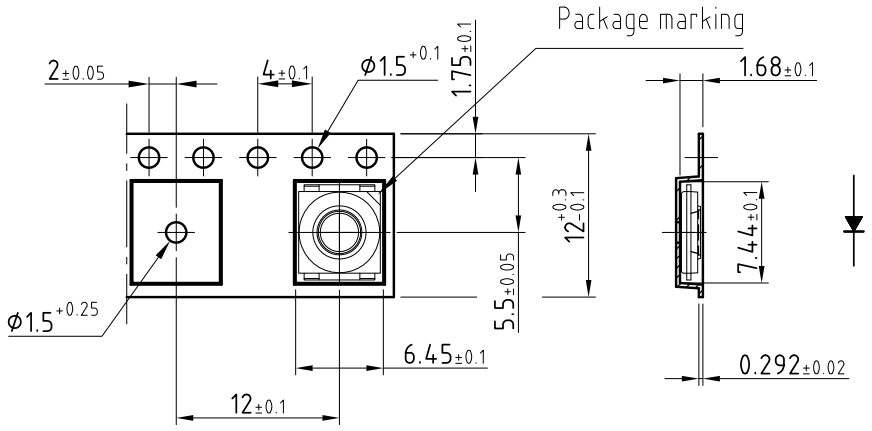


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

TAPING DIMENSIONS in millimeters



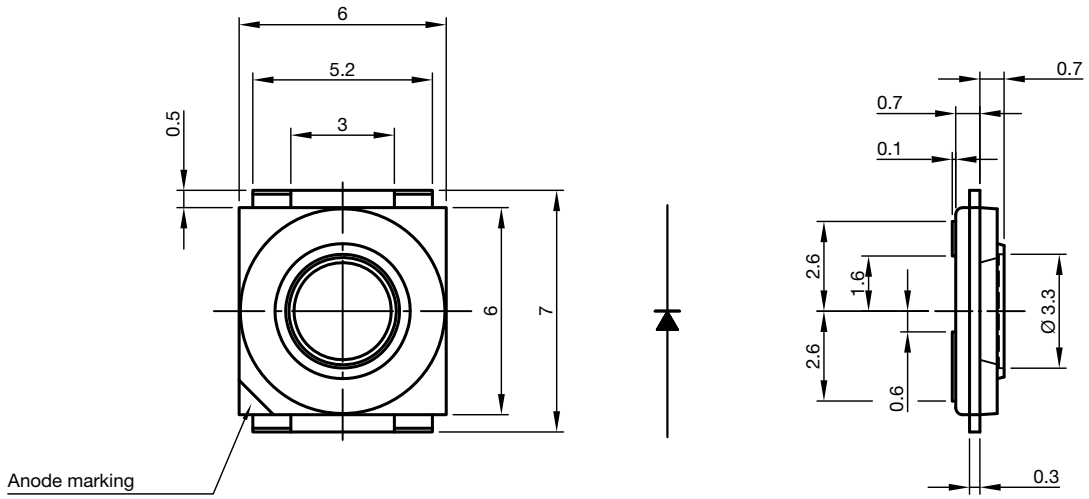


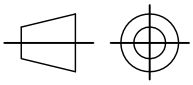


Drawing-No.: 9.800-5094.01-4
Issue: 3; 22.01.08

20846

PACKAGE DIMENSIONS in millimeters



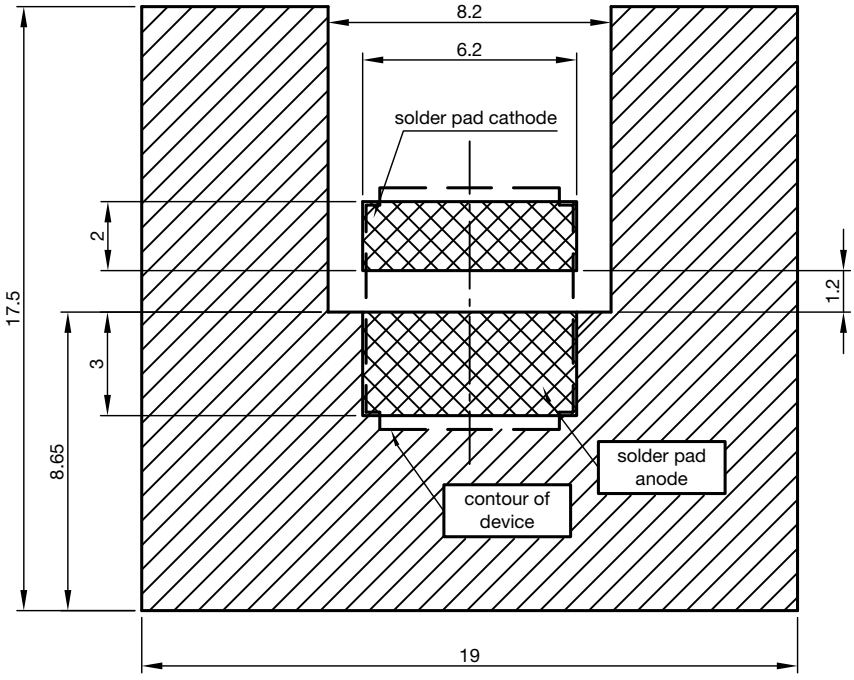


technical drawings
according to DIN
specifications

Recommended solder pad

Recommended area for heat sink
connected with anode pad

Not indicated tolerances ± 0.1



Drawing-No.: 6.541-5076.01-4
Issue: 3; 22.10.14

SOLDER PROFILE

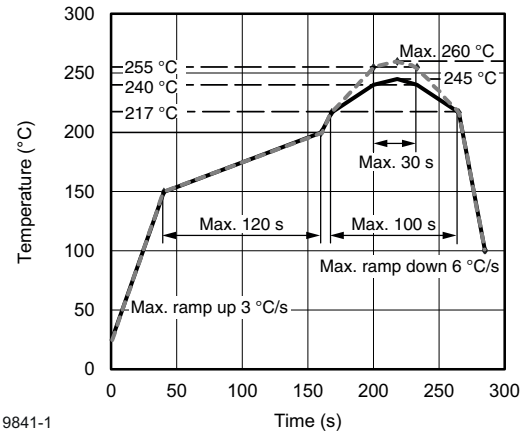


Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020 for Preconditioning According to JEDEC®, Level 2

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 1 year

Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 2, according to J-STD-020B

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

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